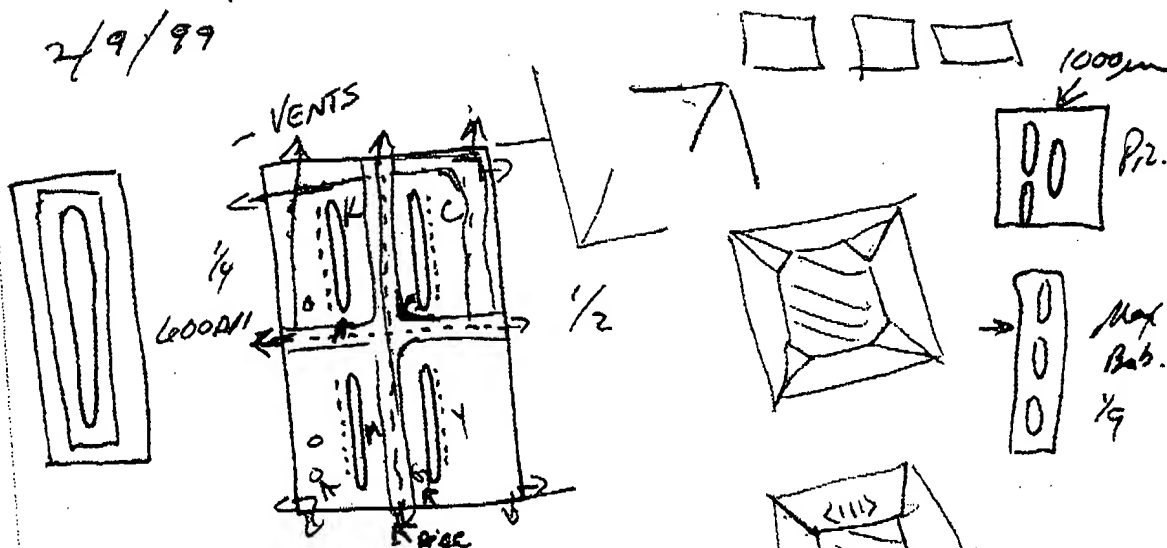
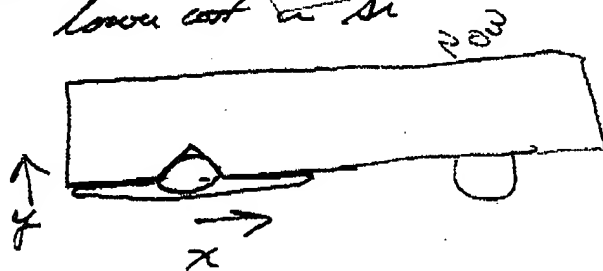


2/9/99



Micro-machining a base ablate a Dice
 trench around ink vics to provide
 containment for die bond.
 - thinner bonding in x & y
 lower cost in Si

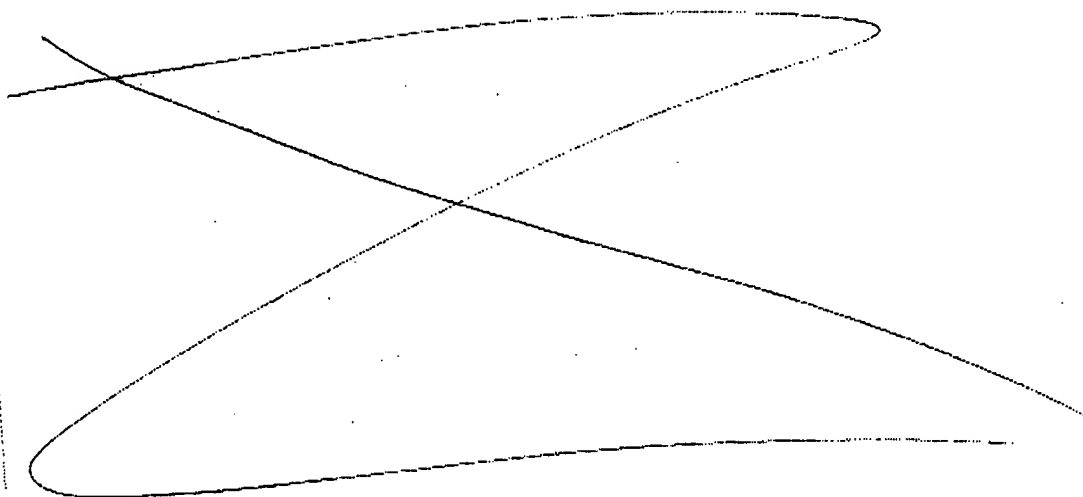


KENT UBERACKER

Jim Spivey 7/2/99
 Carl Sullivan 2/9/99

Problem:

Fragility of the chip



BEST AVAILABLE COPY